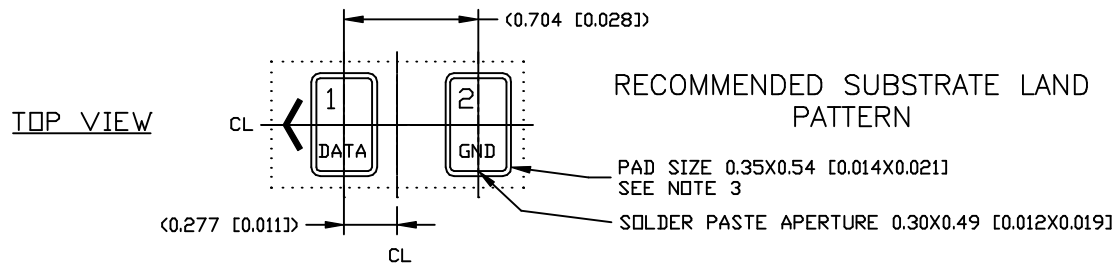
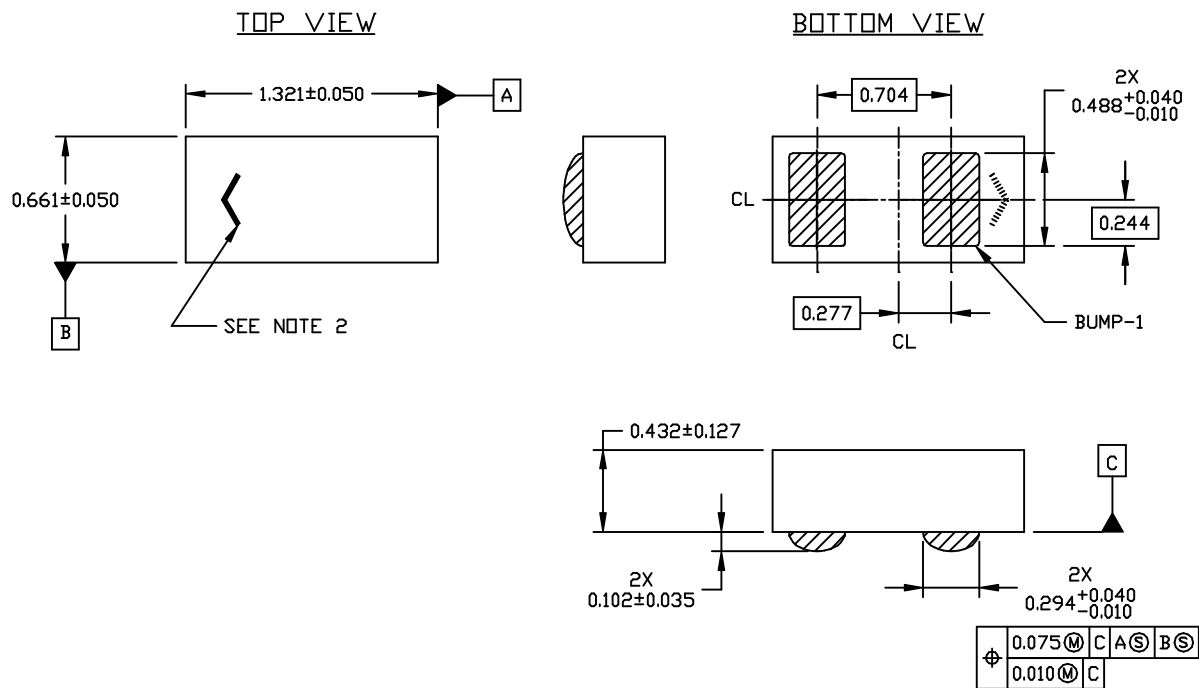



NOTES:

1. DIMENSIONS: MM [INCH]
2. LASER MARK
3. LANDING PAD NOT DEFINED BY SOLDER MASK



SIGNATURE		DATE		 <p>DS2401X1 CHIP SCALE PACKAGE</p>							
QA APVD :								SIZE	FSCM NO.	DWG NO.	REV
ENGR MGR:								A		DS2401X1	A
ENGR BY:								SCALE	SHEET		
CHECK BY:								NONE	1 / 1		
DRAWN BY:											